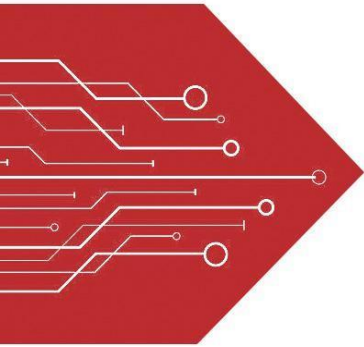


MSKSEMI

SEMICONDUCTOR



ESD



TVS



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MOV



GDT



PLED

Product data sheet

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FEATURES

- ▶ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ▶ For surface mounted applications
- ▶ Metal silicon junction, majority carrier conduction
- ▶ Low power loss, high efficiency
- ▶ Built-in strain relief, ideal for automated placement
- ▶ High forward surge current capability
- ▶ High temperature soldering guaranteed: 250°C/10 seconds at terminals



SMA

MECHANICAL DATA

Case: JEDEC DO-214AC molded plastic body
Terminals: leads solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight: 0.003 ounce, 0.093 grams
 0.004 ounce, 0.111 grams SMA(H)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

CHARACTERISTICS	SYMBOL	SS52	SS53	SS54	SS55	SS56	SS58	SS510	SS515	SS520	UNIT
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS Voltage	V _{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	30	40	50	60	80	100	150	200	V
Maximum Average Forward Rectified Current 0.375" (9.5mm) Lead Lengths	I <sub(av)< sub=""></sub(av)<>	5.0									A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load(JEDEC Method)	I _{FSM}	100									A
Maximum Forward Voltage at 5.0A DC	V _F	0.55		0.7		0.85		0.95		V	
Maximum DC Reverse Current @T _J =25°C at Rated DC Blocking Voltage @T _J =100°C	I _R	0.2		20		1.0		50		mA	
Typical Junction Capacitance (Note1)	C _J	500		350		pF					
Typical Thermal Resistance (Note2)	R _{θJA}	15		10		°C/W					
Operating Temperature Range	T _J	-55 to +150									°C
Storage Temperature Range	T _{STG}	-55 to +150									°C

NOTES: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC

2. Thermal resistance junction to ambient,

FIG. 1 – FORWARD CURRENT DERATING CURVE

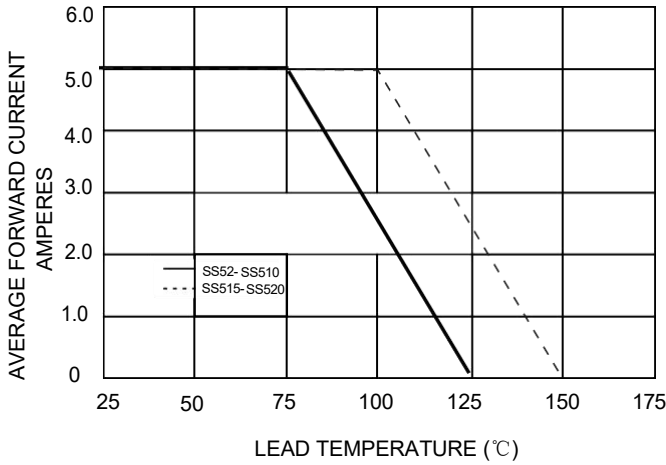


FIG. 2 – MAXIMUM NON-REPETITIVE SURGE CURRENT

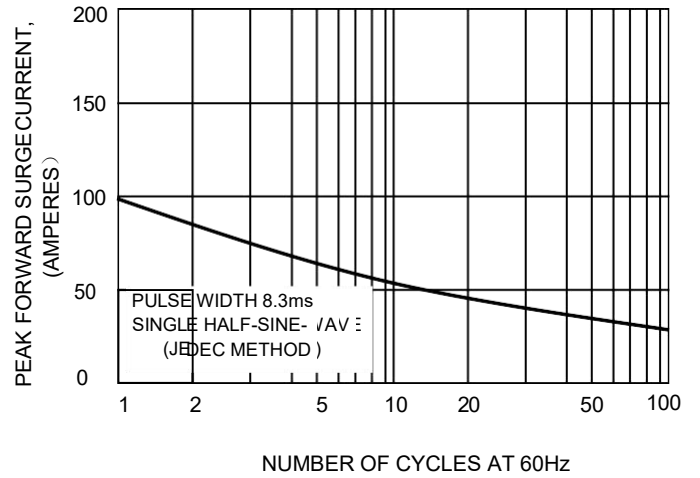


FIG.3 – TYPICAL JUNCTION CAPACITANCE

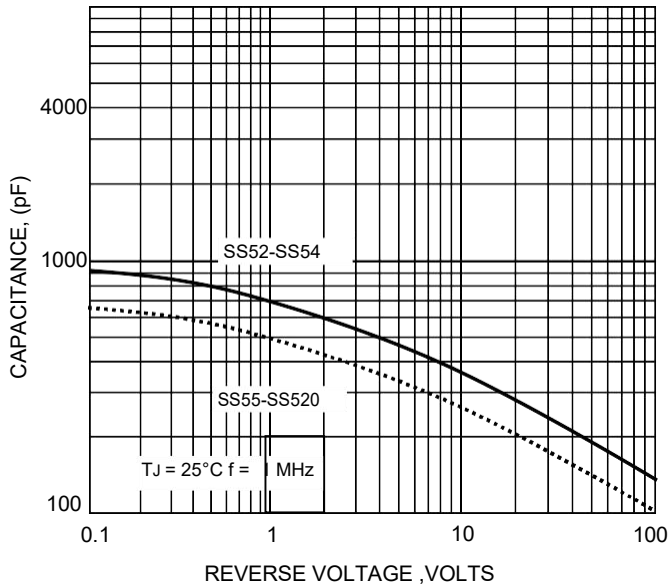


FIG.4-TYPICAL FORWARD CHARACTERISTICS

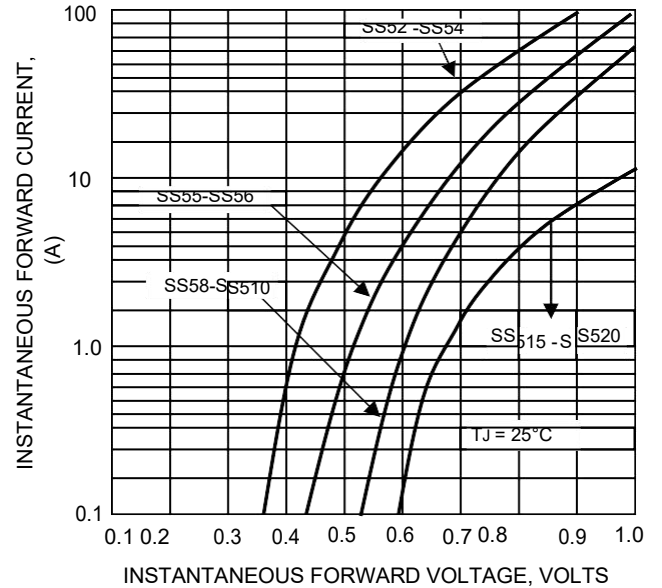
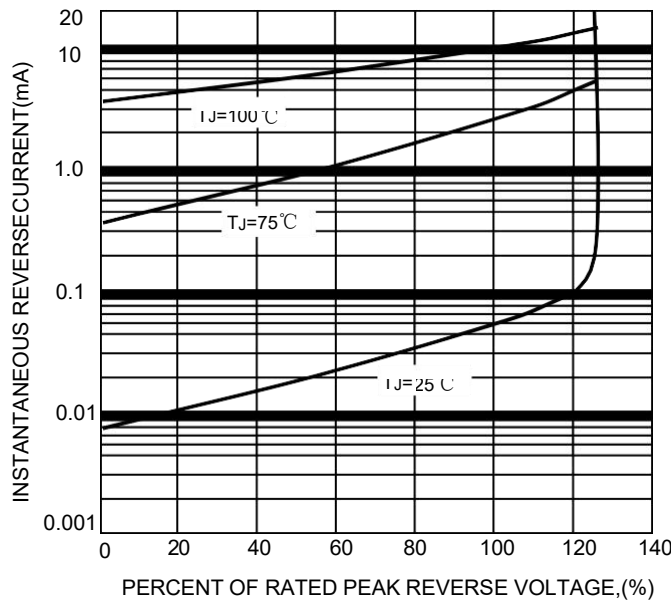
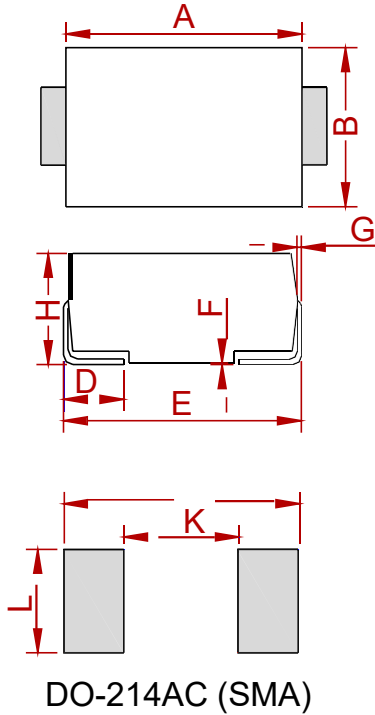


FIG.2-TYPICAL REVER CHARACTERISTICS



PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
SS52 THRU SS520	SMA	2000

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